## **Tentative**

DA36	5103E
Total pages	page

## **DA36103E**

Silicon epitaxial planar type

For high speed switching

Marking Symbol: 24

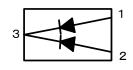
Package Code: ML3-N4-B

Absolute Maximum Ratings Ta = 25 °C

	0				
Parameter		Symbol	Rating	Unit	
Reverse voltage		VR	80	V	
Maximum peak reverse voltage	um peak reverse voltage			V	
Forward current	Single	IF	100	mA	
Forward Current	Double		150	ША	
Peak forward current	Single	IFM	225	mA	
reak lorward current	Double	II-IVI	340	ША	
Non-repetitive peak	Single	IFSM	500	mA	
forward surge current *1	Double	IFSIVI	750	ША	
Junction temperature		Tj	150	°C	
Storage temperature		Tstg	-55 to +150	°C	
N. 1 4 34 1 4	· ·	· ·	·	· ·	

Note: 1. \*1 t = 1 s

### **Internal Connection**



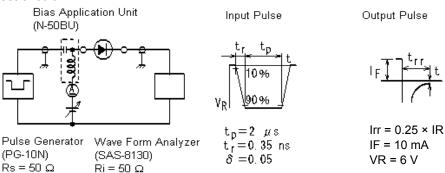
	1.	Anode1
Pin name	2.	Anode2
riii iiaiiie	2	Cathode1
	<del>ن</del>	Cathode2

### Electrical Characteristics Ta = 25 °C±3 °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	VF	IF = 100 mA			1.2	V
Reverse voltage	VR	IR = 100 μA	80			V
Reverse current	IR	VR = 80V			100	nA
Terminal capacitance	Ct	VR = 0 V, f = 1 MHz		2	15	pF
Reverse recovery time *1	trr	IF = 10mA, VR = 6V Irr = 0.25 x IR		2	10	ns

Note: 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.

- 2. Absolute frequency of input and output is 100 MHz.
- 3. \*1 trr test circuit

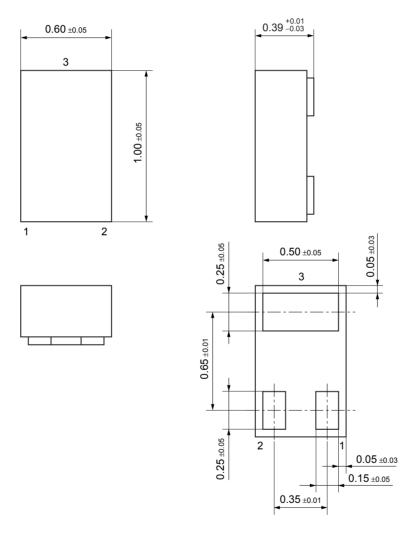


### **Packing**

Embossed type (Thermo-compression sealing): 10 000 pcs / reel

2010.4.7	2010.7.27
Prepared	Revised

ML3-N4-B Unit: mm



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